

**IN THE CLAIMS:**

*Please amend the claims as follows:*

1-12. *(canceled)*

13. *(currently amended)* A mobile phone comprising a system for analysing connection conditions between an integrated circuit package and a circuit board, said system comprising:
- coupling elements coupling said integrated circuit package electrically to said circuit board, and
  - support elements directly connecting said integrated circuit package mechanically with said circuit board using solder balls, ~~wherein said system further comprises:~~
  - ~~means for~~ conductors configured to electrically ~~connecting~~ connect at least two of said support elements with each other on the side of the integrated circuit package,
  - measuring means arranged at said support elements ~~for picking-off and~~ configured to pick-off physical values between said support elements, and
  - evaluation means ~~for evaluating~~ configured to evaluate said physical values to determine mechanical properties of said support elements, and ~~for concluding~~ configured to conclude a condition of said electrical coupling of said integrated circuit package with said circuit board from said determined mechanical properties of said support elements.
14. *(currently amended)* The ~~system~~ mobile phone of claim 13, wherein said support elements are arranged between said circuit board and said integrated circuit package.

15. *(currently amended)* The ~~system~~ mobile phone of claim 13, wherein said support elements are solder pads.
16. *(currently amended)* The ~~system~~ mobile phone of claim 13, wherein said support elements are arranged adjacent to said coupling elements.
17. *(currently amended)* The ~~system~~ mobile phone of claim 13, wherein said support elements are arranged semicircular along said coupling elements.
18. *(currently amended)* The ~~system~~ mobile phone of claim 13, wherein said support elements are arranged along edges and/or at corners of said integrated circuit package.
19. *(currently amended)* The ~~system~~ mobile phone of claim 13, wherein said integrated circuit package is a chip scale package or a chip size package.
20. *(currently amended)* The ~~system~~ mobile phone claim 13, wherein said measuring means provide picking-off electrical conditions of said support elements.
21. *(currently amended)* The ~~system~~ mobile phone claim 13, wherein said measuring means provide picking-off mechanical conditions of said support elements.
22. *(currently amended)* The ~~system~~ mobile phone of claim 13, wherein storage means are comprised to store said picked-off physical values.

23. *(currently amended)* The system mobile phone of claim 13, wherein said evaluation means compare said picked-off physical values with comparative values to determine connection condition.
24. *(currently amended)* The system mobile phone of claim 13, wherein said evaluation means provide an error message in case a poor connection condition is determined.
25. *(currently amended)* The system mobile phone of claim 13, wherein said error message is stored within said storage means.
26. *(currently amended)* The system mobile phone of claim 13, wherein an interface is provided to read out said stored physical values and/or stored error messages.
- 27-29. *(canceled)*
30. *(new)* An apparatus comprising:
- coupling elements coupling an integrated circuit package electrically to a circuit board,
  - support elements directly connecting said integrated circuit package mechanically with said circuit board using solder balls,
  - conductors configured to electrically connect at least two of said support elements with each other on the side of the integrated circuit package,
  - measuring means arranged at said support elements and configured to pick-off physical values between said support elements, and
  - evaluation means configured to evaluate said physical values to determine mechanical properties of said support elements, and configured to conclude a condition of said electrical coupling of said integrated circuit package with said

circuit board from said determined mechanical properties of said support elements.

31. *(new)* The system of claim 30, wherein said support elements are arranged semicircular along said coupling elements.
32. *(new)* The apparatus of claim 30, wherein said support elements are arranged along edges and/or at corners of said integrated circuit package.
33. *(new)* An apparatus comprising:
  - coupling elements coupling an integrated circuit package electrically to a circuit board, and
  - support elements directly connecting said integrated circuit package mechanically with said circuit board using solder balls,
  - means for electrically connecting at least two of said support elements with each other on the side of the integrated circuit package,
  - measuring means arranged at said support elements for picking off physical values between said support elements, and
  - evaluation means for evaluating said physical values to determine mechanical properties of said support elements, and for concluding a condition of said electrical coupling of said integrated circuit package with said circuit board from said determined mechanical properties of said support elements.
34. *(new)* The apparatus of claim 33, wherein said support elements are arranged semicircular along said coupling elements.